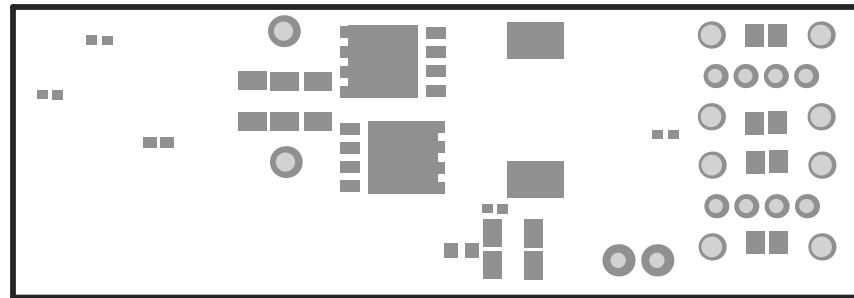
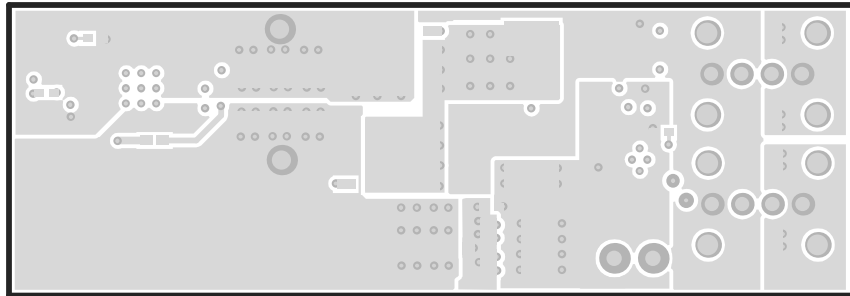


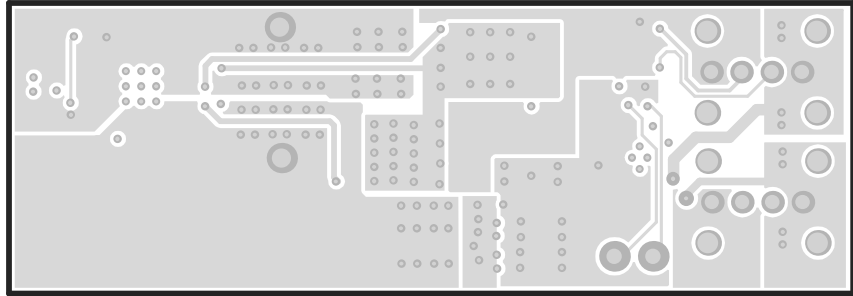
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 3/19/2015 4:39:46 PM	TEXAS INSTRUMENTS	



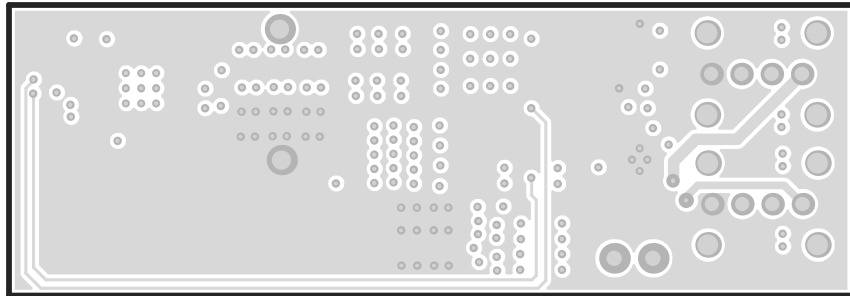
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 3/19/2015 4:39:47 PM	TEXAS INSTRUMENTS	



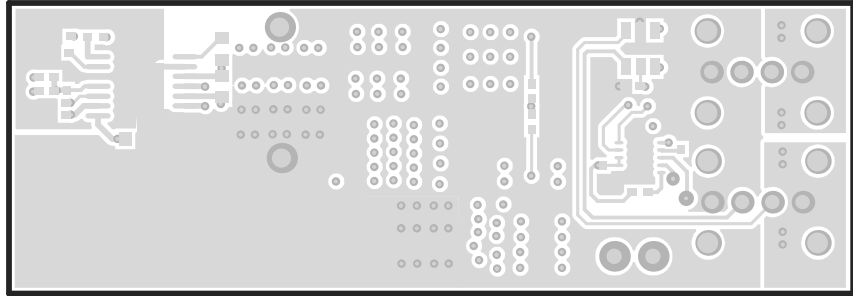
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 3/19/2015 4:39:48 PM	TEXAS INSTRUMENTS	



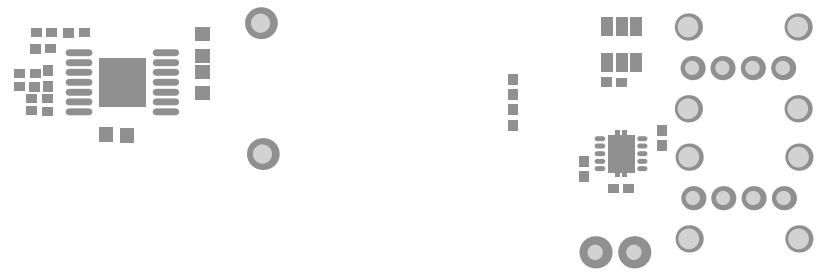
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer1	GENERATED : 3/19/2015 4:39:48 PM	TEXAS INSTRUMENTS	



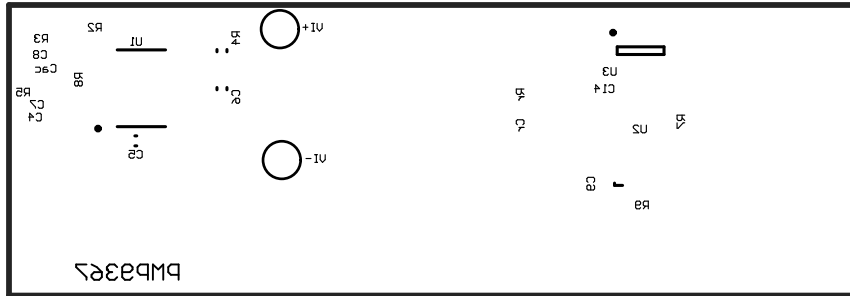
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer2	GENERATED : 3/19/2015 4:39:49 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 3/19/2015 4:39:49 PM	TEXAS INSTRUMENTS	

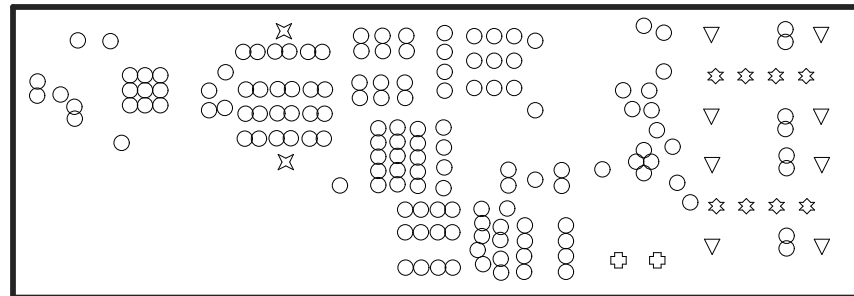


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 3/19/2015 4:39:49 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 3/19/2015 4:39:50 PM	TEXAS INSTRUMENTS	





Symbol	Hit Count	Tool Size	Plated	Hole Type
○	151	11mil (0.279mm)	PTH	Round
☆	8	37.402mil (0.95mm)	PTH	Round
⊕	2	40mil (1.016mm)	PTH	Round
▽	8	53.937mil (1.37mm)	PTH	Round
171 Total				

ALL ARTWORK VIEWED FROM TOP SIDE

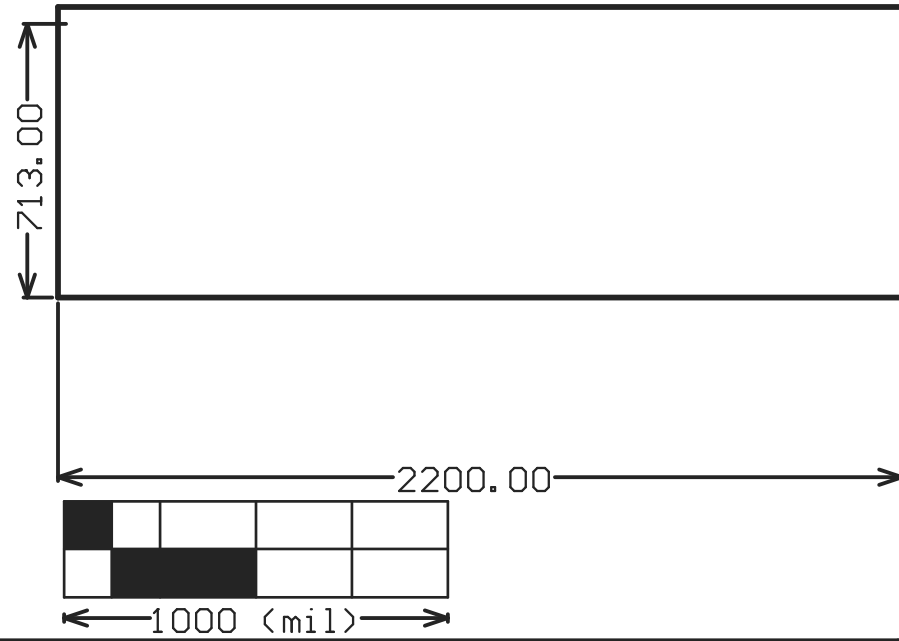
BOARD #: XX#### REV: E1

LAYER NAME = Drill Drawing

PLOT NAME = Drill Drawing

GENERATED : 3/19/2015 4:39:50 PM

49.213mil (1.25mm)	PTH	Round
53.937mil (1.37mm)	PTH	Round
TEXAS INSTRUMENTS		



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 3/19/2015 4:39:51 PM	TEXAS INSTRUMENTS	

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